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documents or copy thereof.

1. Name of conveying party(ies):

1. Martin Kerber

(Additional name(s) of conveying party(ies) attached)  Yes  No

2. Name and address of receiving party(ies)

Name: Siemens Aktiengesellschaft

Internal Address: ZT GG VM

Street Address: Postfach 22 16 34

City: München State: Germany ZIP: 80506

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3. Nature of conveyance:

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Execution Date: March 24, 1998

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)

09/044,533

B. Patent No.(s)

Additional numbers attached  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Lerner and Greenberg, P.A.

Internal Address: \_\_\_\_\_

Street Address: P.O. Box 2480

City: Hollywood State: FL ZIP: 33022

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41) ..... \$ 40.00

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**PATENT**  
**REEL: 010513 FRAME: 0270**

Docket No.: GR 95 P 1932

### ASSIGNMENT

WHEREAS I, MARTIN KERBER, residing at München, Federal Republic of Germany, have invented certain new and useful improvements in a

#### METHOD FOR PRODUCING VERY SMALL STRUCTURAL WIDTHS ON A SEMICONDUCTOR SUBSTRATE

for which an application for Letters Patent of the United States of America was executed on the date of execution of this assignment;

WHEREAS, SIEMENS AKTIENGESELLSCHAFT, a German corporation doing business at München, Federal Republic of Germany, is desirous of acquiring the entire interest in the invention, and in any and all Letters Patent of the United States that may be obtained therefor;

NOW, THEREFORE, be it known that for and in consideration of my employment by the said corporation and other valuable consideration, the receipt and sufficiency whereof are hereby acknowledged, I have sold, assigned and transferred, and by these presents do sell, assign and transfer unto the said corporation, its legal representative, successors and assigns, the full and exclusive right to the said invention as fully set forth and described in the above-mentioned application, and to the application and any and all divisions and continuations thereof, and any and all Letters Patent of the United States which may be granted therefore, and any and all reissues of the Letters Patent, the same to be held and enjoyed by the said corporation, its legal representatives, successors and assigns, to the full end of the term for which the Letters Patent may be granted or may be reissued or extended, as fully and entirely as the same would have been held by me had this assignment and sale not been made.

AND I hereby authorize the Commissioner of Patents to issue any and all Letters Patent of the United States on the invention or resulting from the application and from any and all divisions and continuations thereof of the said corporation as the assignee of the entire right, title and interest in and to the same.

IN TESTIMONY WHEREOF, I have hereunto set my hand and seal this day of April, 1998.

In the presence of:

*[Signature]*  
*[Signature]*

*Martin Kerber* (L.S.)  
MARTIN KERBER